

PART INFORMATION

Mfg Item Number	C291NSE7FHA
Mfg Item Name	FC BGA 780 29*29*2.68 P1

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2014-02-14
Response Document ID	00DLK50008S285A1.4
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
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Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	C291NSE7FHA
Mfg Item Name	FC BGA 780 29*29*2.68 P1
Version	ALL
Weight	5.435600
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	250 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Bonding Agent	0.031						g				
Bonding Agent		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.01395	g	450000	45	2566	0.2566
Bonding Agent		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.0124	g	400000	40	2281	0.2281
Bonding Agent		Solvents, additives, and other materials	Dimethylsilylated and trimethylated silica	68988-89-6		0.00465	g	150000	15	855	0.0855
Die Encapsulant, Filler	0.031						g				
Die Encapsulant, Filler		Metals	Aluminum, metal	7429-90-5		0.02232	g	720000	72	4106	0.4106
Die Encapsulant, Filler		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.00279	g	90000	9	513	0.0513
Die Encapsulant, Filler		Metals	Zinc oxide	1314-13-2		0.00558	g	180000	18	1026	0.1026
Die Encapsulant, Filler		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.00031	g	10000	1	57	0.0057
Solder Balls - Lead Free	0.6533						g				
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.00327238	g	5009	0.5009	602	0.0602
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.01963428	g	30054	3.0054	3612	0.3612
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.63039334	g	964937	96.4937	115974	11.5974
Underfill	0.036						g				
Underfill		Bismuth/Bismuth Compounds	Bismuth nitrate	10361-44-1		0.00018	g	5000	0.5	33	0.0033
Underfill		Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.00018	g	5000	0.5	33	0.0033
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.0054	g	150000	15	993	0.0993
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.0036	g	100000	10	662	0.0662
Underfill		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00018	g	5000	0.5	33	0.0033
Underfill		Plastics/polymers	4,4'-Isopropylidenediphenol-1-chloro-2,3-epoxypropane (Doricentral)	25068-38-6		0.00108	g	30000	3	198	0.0198
Underfill		Glass	Silica, vitreous	60676-86-0		0.0216	g	600000	60	3973	0.3973
Underfill		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.00018	g	5000	0.5	33	0.0033
Underfill		Solvents, additives, and other materials	Proprietary Material-Other aliphatic amine compounds	-		0.0036	g	100000	10	662	0.0662
Organic Substrate, Halogen-free	0.7375						g				
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Proprietary Material-Other acrylonitrile compounds	-		0.07198634	g	97473	9.7473	13225	1.3225
Organic Substrate, Halogen-free		Arsenic/Arsenic Compounds	Arsenic	7440-39-2		0.00000738	g	10	0.001	1	0.0001
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.00267123	g	3622	0.3622	491	0.0491
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.4074702	g	552502	55.2502	74963	7.4963
Organic Substrate, Halogen-free		Lead/Lead Compounds	Lead	7439-92-1		0.00000443	g	6	0.0006	0	0
Organic Substrate, Halogen-free		Glass	Fibrous glass-wool	65997-17-3		0.23251015	g	315268	31.5268	42775	4.2775
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.01452359	g	19693	1.9693	2671	0.2671
Organic Substrate, Halogen-free		Metals	Silver, metal	7440-22-4		0.00025444	g	345	0.0345	46	0.0046
Organic Substrate, Halogen-free		Metals	Tin, metal	7440-31-5		0.00817224	g	11081	1.1081	1503	0.1503
Heat Spreader	3.8259						g				
Heat Spreader		Metals	Copper, metal	7440-50-8		3.59713414	g	940206	94.0206	661786	66.1786
Heat Spreader		Nickel (external applications only)	Nickel	7440-02-0		0.22876566	g	59794	5.9794	42086	4.2086
Pb-free Bumped Semiconductor D	0.1209						g				
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.0006045	g	5000	0.5	111	0.0111
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4		0.00039084	g	3150	0.315	70	0.007
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.01050017	g	86850	8.685	1931	0.1931
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0010881	g	9000	0.9	200	0.02
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-		0.10832639	g	896000	89.6	19929	1.9929

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/C291NSE7FHA_IPC1752_v11.xml

http://www.freescale.com/mcdfs/C291NSE7FHA_IPC1752A.xml